

Low profile linear silicon NPN RF bipolar transistor









Product description

The BFR380L3 is a low noise device based on Si that is part of Infineon's established third generation RF bipolar transistor family. Its high transition frequency and low current and low noise characteristics make the device suitable for a broad range of applications as high as 3.5 GHz. It remains cost competitive without compromising on ease of use.



Feature list

- Minimum noise figure NF_{min} = 1.1 dB at 1.8 GHz, 3 V, 8 mA
- High gain G_{ma} = 14 dB at 1.8 GHz, 3 V, 40 mA
- OIP₃ = 29.5 dBm at 1.8 GHz, 3 V, 40 mA

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

- Low noise amplifiers (LNAs) for DVB-T/H
- LNAs for TV white space application
- Low noise, high linearity amplifiers for sub-1 GHz ISM band applications

Device information

Table 1 Part information

Product name / Ordering code	Package	Pin configuration		onfiguration Marking		Pieces / Reel
BFR380L3 / BFR380L3E6327XTMA1	TSLP-3-1	1 = B	2 = E	3 = C	FC	15000

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions

Low profile linear silicon NPN RF bipolar transistor



Table of contents

Table of contents

	Product description	. 1
	Feature list	1
	Product validation	1
	Potential applications	1
	Device information	1
	Table of contents	2
1	Absolute maximum ratings	3
2	Thermal characteristics	4
3	Electrical characteristics	5
3.1	DC characteristics	5
3.2	General AC characteristics	
3.3	Frequency dependent AC characteristics	
4	Package information TSLP-3-1	. 7
	Revision history	8
	Disclaimer	c

Low profile linear silicon NPN RF bipolar transistor



Absolute maximum ratings

1 Absolute maximum ratings

Table 2 Absolute maximum ratings at $T_A = 25$ °C (unless otherwise specified)

Parameter	Symbol	Values		Unit	Note or test condition	
		Min.	Max.			
Collector emitter voltage	V_{CEO}	_	6	٧	Open base	
Collector emitter voltage	V _{CES}		15		E-B short circuited	
Collector base voltage	V _{CBO}		15		Open emitter	
Emitter base voltage	V_{EBO}		2		Open collector	
Base current	I _B		14	mA	-	
Collector current	I _C		80			
Total power dissipation ¹⁾	P _{tot}	1	380	mW	<i>T</i> _S ≤ 96 °C	
Junction temperature	TJ	1	150	°C	-	
Storage temperature	T_{Stg}	-55				

Attention: Stresses above the max. values listed here may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit

 Datasheet
 3
 Revision 2.0

 2019-01-25
 2019-01-25

 T_S is the soldering point temperature. T_S is measured on the emitter lead at the soldering point of the PCB.



Thermal characteristics

2 Thermal characteristics

Table 3 Thermal resistance

Parameter	Symbol	Values			Values U		Unit	Note or test condition
		Min.	Тур.	Max.				
Junction - soldering point	R _{thJS}	_	140	_	K/W	-		

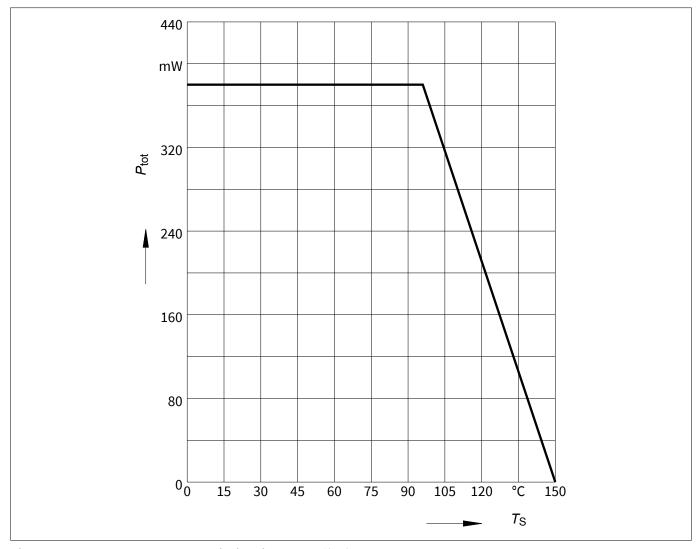


Figure 1 Total power dissipation $P_{\text{tot}} = f(T_S)$

Low profile linear silicon NPN RF bipolar transistor



Electrical characteristics

3 Electrical characteristics

3.1 DC characteristics

Table 4 DC characteristics at $T_A = 25$ °C (unless otherwise specified)

Parameter	Symbol	Values			Unit	Note or test condition	
		Min.	Тур.	Max.			
Collector emitter breakdown voltage	V _{(BR)CEO}	6	9	-	V	$I_C = 1 \text{ mA}, I_B = 0,$ open base	
Collector emitter leakage current	I _{CES}	-	1	30 ²⁾	nA	$V_{CE} = 5 \text{ V}, V_{BE} = 0,$ E-B short circuited	
			_	1000 2)		$V_{CE} = 15 \text{ V}, V_{BE} = 0,$ E-B short circuited	
Collector base leakage current	I _{CBO}			30 ²⁾		$V_{\text{CB}} = 5 \text{ V}, I_{\text{E}} = 0,$ open emitter	
Emitter base leakage current	I _{EBO}		10	500 ²⁾		$V_{\text{EB}} = 1 \text{ V}, I_{\text{C}} = 0,$ open collector	
DC current gain	h _{FE}	90	120	160		$V_{\text{CE}} = 3 \text{ V}, I_{\text{C}} = 40 \text{ mA},$ pulse measured	

3.2 General AC characteristics

Table 5 General AC characteristics at $T_A = 25 \,^{\circ}\text{C}$

Parameter	Symbol	Symbol Values			Unit	Note or test condition	
		Min.	Тур.	Max.			
Transition frequency	f_{T}	11	14	-	GHz	$V_{CE} = 3 \text{ V}, I_{C} = 40 \text{ mA},$ f = 1 GHz	
Collector base capacitance	C _{CB}	_	0.45	0.8	pF	$V_{CB} = 5 \text{ V}, V_{BE} = 0,$ f = 1 MHz, emitter grounded	
Collector emitter capacitance	C _{CE}		0.18	_		$V_{CE} = 5 \text{ V}, V_{BE} = 0,$ f = 1 MHz, base grounded	
Emitter base capacitance	C _{EB}		1			$V_{\text{EB}} = 0.5 \text{ V}, V_{\text{CB}} = 0,$ f = 1 MHz, collector grounded	

² Maximum values not limited by the device but by the short cycle time of the 100% test.



Electrical characteristics

Frequency dependent AC characteristics 3.3

Measurement setup is a test fixture with Bias-T's in a 50 Ω system, T_A = 25 °C.

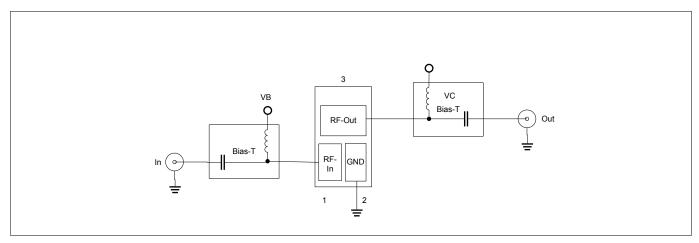


Figure 2 **Testing circuit**

Table 6 AC characteristics, $V_{CE} = 3 \text{ V}$, f = 1.8 GHz

Parameter	Symbol Values U			Unit	Note or test condition	
		Min.	Тур.	Max.		
Power gain					dB	
Maximum power gain	G _{ma}	11.5	14	16.5		$I_{\rm C} = 40 {\rm mA}$
Transducer gain	$ S_{21} ^2$	9.5	11.5	13.5		
Noise figure						
Minimum noise figure	NF _{min}	0.5	1.1	2.1		$I_{\rm C}$ = 8 mA
Linearity		_		_	dBm	I _C = 40 mA,
3rd order intercept point at output	OIP ₃		29.5			$I_{\rm C} = 40 \text{ mA},$ $Z_{\rm S} = Z_{\rm L} = 50 \Omega,$
• 1 dB gain compression point at output	OP _{1dB}		16			
	OP _{1dB}		19.5			$Z_{\rm S} = Z_{\rm S,opt}, Z_{\rm L} = Z_{\rm L,opt}$

AC characteristics, $V_{CE} = 3 \text{ V}$, f = 3 GHzTable 7

Parameter	Symbol	Values		Values Ur		Note or test condition
		Min.	Тур.	Max.		
Power gain					dB	
Maximum power gain	G_{ma}	7.5	10	12.5		$I_{\rm C} = 40 {\rm mA}$
Transducer gain	$ S_{21} ^2$	5.5	7.5	9.5		

Note:

 $G_{
m ms}$ = $IS_{21}/S_{12}I$ for k < 1; $G_{
m ma}$ = $IS_{21}/S_{12}I$ (k-(k^2 -1) $^{1/2}$) for k > 1. In order to get the NF $_{
m min}$ values stated in this chapter, the test fixture losses have been subtracted from all measured results. OIP_3 value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50 Ω from 0.1 MHz to 6 GHz.



Package information TSLP-3-1

4 Package information TSLP-3-1

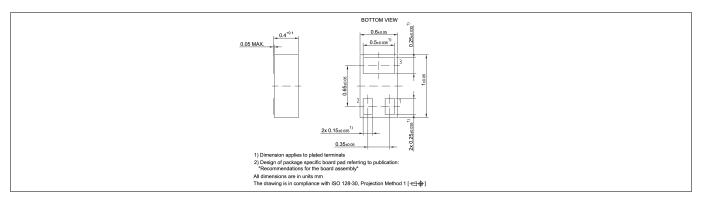


Figure 3 Package outline

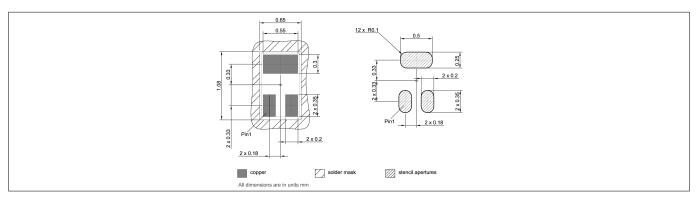


Figure 4 Foot print

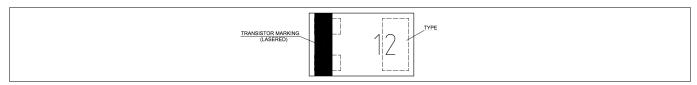


Figure 5 Marking layout example

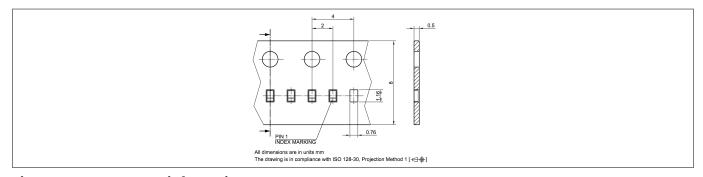


Figure 6 Tape information

Note: See our Recommendations for Printed Circuit Board Assembly of TSLP/TSSLP/TSNP Packages.

The marking layout is an example. For the real marking code refer to the device information on the first page. The number of characters shown in the layout example is not necessarily the real one. The marking layout can consist of less characters.

Low profile linear silicon NPN RF bipolar transistor



Revision history

Revision history

Document version	Date of release	Description of changes
Revision 2.0	2019-01-25	New datasheet layout.

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

Edition 2019-01-25 Published by Infineon Technologies AG 81726 Munich, Germany

© 2019 Infineon Technologies AG All Rights Reserved.

Do you have a question about any aspect of this document?

 ${\bf Email: erratum@infineon.com}$

Document reference IFX-uuc1526275534524

IMPORTANT NOTICE

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

WARNINGS

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury